

[ABSTRACT]

A film adhesive (13) of the present invention is a curable film adhesive, wherein either an uncured single layer of the film adhesive (13) having a thickness of 60 μm , or a
5 laminate formed by laminating two or more uncured layers of the film adhesive (13) so that a total thickness becomes 60 μm , has an elongation at break at 0°C of equal to or less than 60%, and an adhesive force of the uncured film adhesive (13) with respect to a semiconductor wafer is equal to or more than 300 mN / 25 mm.

A semiconductor processing sheet (1) of the present invention is formed by
10 providing the film adhesive (13) on a support sheet (10) having a base material (11).